

---

# HD74ALVCH162830

## 1-bit to 2-bit Address Driver with 3-state Outputs

REJ03D0040-0200Z  
(Previous ADE-205-197(Z))  
Rev.2.00  
Oct.02.2003

---

### Description

This 1-bit to 2-bit address driver is designed for 2.3 V to 3.6 V  $V_{CC}$  operation. To ensure the high impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current sinking capability of the driver. Active bus hold circuitry is provided to hold unused or floating inputs at a valid logic level. All outputs, which are designed to sink up to 12 mA, include equivalent 26  $\Omega$  resistors to reduce overshoot and undreshoot.

### Features

- $V_{CC} = 2.3 \text{ V to } 3.6 \text{ V}$
- Typical  $V_{OL}$  ground bounce  $< 0.8 \text{ V}$  (@ $V_{CC} = 3.3 \text{ V}$ ,  $T_a = 25^\circ\text{C}$ )
- Typical  $V_{OH}$  undershoot  $> 2.0 \text{ V}$  (@ $V_{CC} = 3.3 \text{ V}$ ,  $T_a = 25^\circ\text{C}$ )
- High output current  $\pm 12 \text{ mA}$  (@ $V_{CC} = 3.0 \text{ V}$ )
- Bus hold on data inputs eliminates the need for external pullup / pulldown resistors
- All outputs have equivalent 26  $\Omega$  series resistors, so no external resistors are required

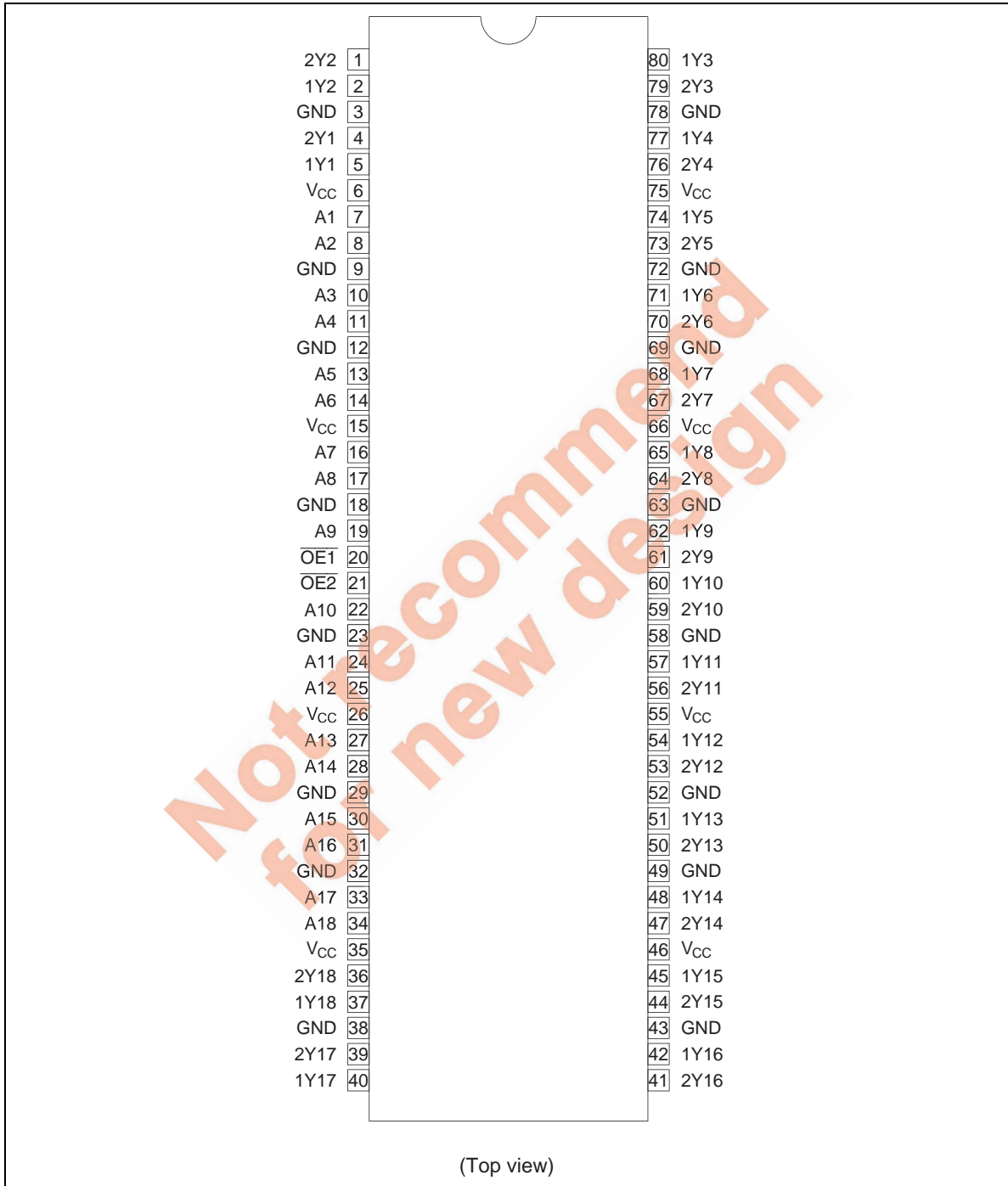
**Function Table**

Inputs			Outputs	
$\overline{OE1}$	$\overline{OE2}$	A	1Yn	2Yn
L	H	H	H	Z
L	H	L	L	Z
H	L	H	Z	H
H	L	L	Z	L
L	L	H	H	H
L	L	L	L	L
H	H	X	Z	Z

H : High level  
 L : Low level  
 X : Immaterial  
 Z : High impedance

Not recommend  
 for new design

Pin Arrangement



### Absolute Maximum Ratings

Item	Symbol	Ratings	Unit	Conditions
Supply voltage	$V_{CC}$	-0.5 to 4.6	V	
Input voltage <sup>*1</sup>	$V_I$	-0.5 to 4.6	V	
Output voltage <sup>*1, 2</sup>	$V_O$	-0.5 to $V_{CC} + 0.5$	V	
Input clamp current	$I_{IK}$	-50	mA	$V_I < 0$
Output clamp current	$I_{OK}$	±50	mA	$V_O < 0$ or $V_O > V_{CC}$
Continuous output current	$I_O$	±50	mA	$V_O = 0$ to $V_{CC}$
$V_{CC}$ , GND current / pin	$I_{CC}$ or $I_{GND}$	±100	mA	
Maximum power dissipation at $T_a = 55^\circ\text{C}$ (in still air) <sup>*3</sup>	$P_T$	1	W	TVSOP
Storage temperature	$T_{stg}$	-65 to 150	°C	

Notes: Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute maximum rated conditions for extended periods may affect device reliability.

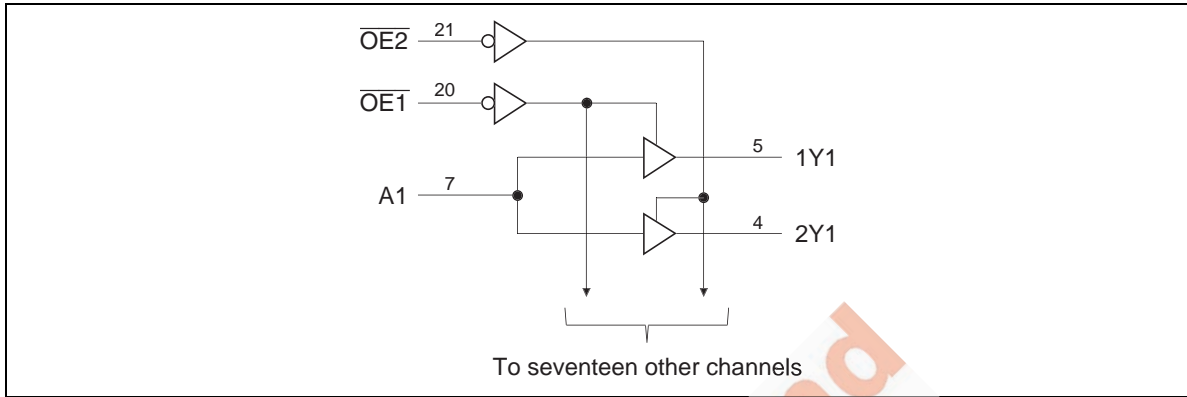
1. The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.
2. This value is limited to 4.6 V maximum.
3. The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.

### Recommended Operating Conditions

Item	Symbol	Min	Max	Unit	Conditions
Supply voltage	$V_{CC}$	2.3	3.6	V	
Input voltage	$V_I$	0	$V_{CC}$	V	
Output voltage	$V_O$	0	$V_{CC}$	V	
High level output current	$I_{OH}$	—	-6	mA	$V_{CC} = 2.3\text{ V}$
		—	-8		$V_{CC} = 2.7\text{ V}$
		—	-12		$V_{CC} = 3.0\text{ V}$
Low level output current	$I_{OL}$	—	6	mA	$V_{CC} = 2.3\text{ V}$
		—	8		$V_{CC} = 2.7\text{ V}$
		—	12		$V_{CC} = 3.0\text{ V}$
Input transition rise or fall rate	$\Delta t / \Delta v$	0	10	ns / V	
Operating temperature	$T_a$	-40	85	°C	

Note: Unused control inputs must be held high or low to prevent them from floating.

**Logic Diagram**



Not recommend  
for new design

**Electrical Characteristics**

(Ta = -40 to 85°C)

Item	Symbol	V <sub>CC</sub> (V)	Min	Max	Unit	Test Conditions			
Input voltage	V <sub>IH</sub>	2.3 to 2.7	1.7	—	V				
		2.7 to 3.6	2.0	—					
	V <sub>IL</sub>	2.3 to 2.7	—	0.7					
		2.7 to 3.6	—	0.8					
Output voltage	V <sub>OH</sub>	2.3 to 3.6	V <sub>CC</sub> -0.2	—	V	I <sub>OH</sub> = -100 μA			
		2.3	1.9	—		I <sub>OH</sub> = -4 mA, V <sub>IH</sub> = 1.7 V			
		2.3	1.7	—		I <sub>OH</sub> = -6 mA, V <sub>IH</sub> = 1.7 V			
		3.0	2.4	—		I <sub>OH</sub> = -6 mA, V <sub>IH</sub> = 2.0 V			
		2.7	2.0	—		I <sub>OH</sub> = -8 mA, V <sub>IH</sub> = 2.0 V			
		3.0	2.0	—		I <sub>OH</sub> = -12 mA, V <sub>IH</sub> = 2.0 V			
	V <sub>OL</sub>	2.3 to 3.6	—	0.2		I <sub>OL</sub> = 100 μA			
		2.3	—	0.4		I <sub>OL</sub> = 4 mA, V <sub>IL</sub> = 0.7 V			
		2.3	—	0.55		I <sub>OL</sub> = 6 mA, V <sub>IL</sub> = 0.7 V			
		3.0	—	0.55		I <sub>OL</sub> = 6 mA, V <sub>IL</sub> = 0.8 V			
		2.7	—	0.6		I <sub>OL</sub> = 8 mA, V <sub>IL</sub> = 0.8 V			
		3.0	—	0.8		I <sub>OL</sub> = 12 mA, V <sub>IL</sub> = 0.8 V			
		Input current	I <sub>IN</sub>	3.6		—	±5	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND
				2.3		45	—		V <sub>IN</sub> = 0.7 V
2.3	-45			—	V <sub>IN</sub> = 1.7 V				
3.0	75			—	V <sub>IN</sub> = 0.8 V				
3.0	-75			—	V <sub>IN</sub> = 2.0 V				
3.6	—			±500	V <sub>IN</sub> = 0 to 3.6 V <sup>*1</sup>				
Off state output current	I <sub>OZ</sub>	3.6	—	±10	μA	V <sub>OUT</sub> = V <sub>CC</sub> or GND			
Quiescent supply current	I <sub>CC</sub>	3.6	—	40	μA	V <sub>IN</sub> = V <sub>CC</sub> or GND			
	ΔI <sub>CC</sub>	3.0 to 3.6	—	750	μA	V <sub>IN</sub> = one input at (V <sub>CC</sub> -0.6) V, other inputs at V <sub>CC</sub> or GND			

Note: 1. This is the bus hold maximum dynamic current required to switch the input from one state to another.

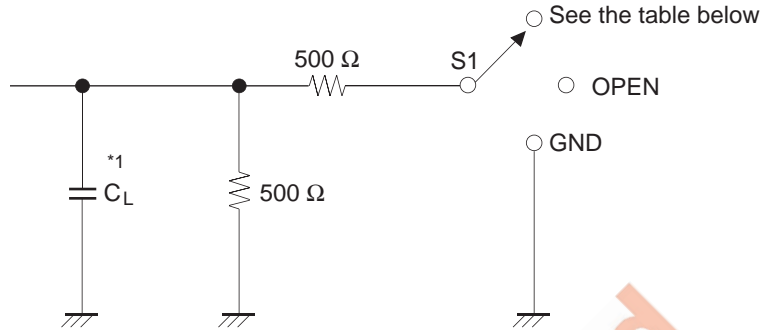
### Switching Characteristics

(Ta = -40 to 85°C)

Item	Symbol	V <sub>CC</sub> (V)	Min	Typ	Max	Unit	FROM (Input)	TO (Output)
Propagation delay time	t <sub>PLH</sub>	2.5±0.2	1.2	—	3.8	ns	A	Y
	t <sub>PHL</sub>	2.7	—	—	4.0			
		3.3±0.3	1.7	—	3.5			
Output enable time	t <sub>ZH</sub>	2.5±0.2	1.0	—	5.7	ns	OE	Y
	t <sub>ZL</sub>	2.7	—	—	5.7			
		3.3±0.3	1.0	—	4.8			
Output disable time	t <sub>HZ</sub>	2.5±0.2	1.5	—	6.2	ns	OE	Y
	t <sub>LZ</sub>	2.7	—	—	5.4			
		3.3±0.3	1.7	—	5.2			
Input capacitance	C <sub>IN</sub>	3.3	—	4.5	—	pF	Control inputs	
		3.3	—	5.0	—		Data inputs	
Output capacitance	C <sub>O</sub>	3.3	—	7.5	—	pF		

Not recommended for new design

Test Circuit



Load Circuit for Outputs

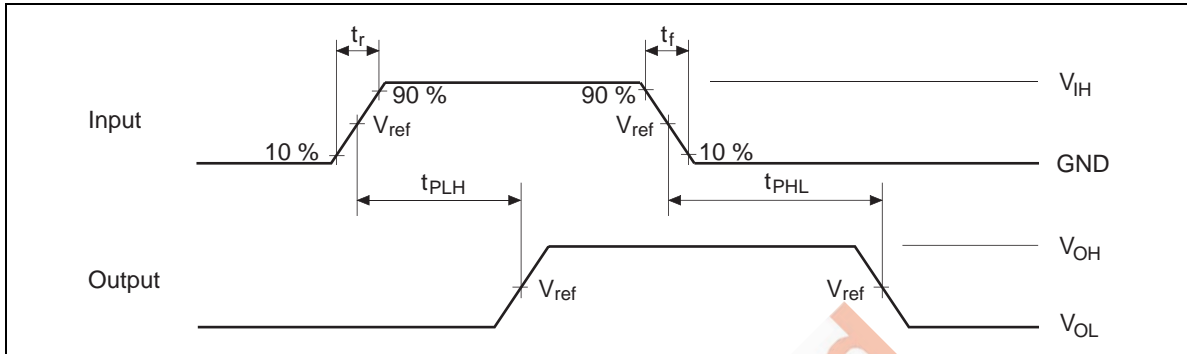
Symbol	$V_C = 2.5 \pm 0.2 \text{ V}$	$V_{CC} = 2.7 \text{ V}, 3.3 \pm 0.3 \text{ V}$
$t_{PLH} / t_{PHL}$	OPEN	OPEN
$t_{ZH} / t_{HZ}$	GND	GND
$t_{ZL} / t_{LZ}$	$2 \times V_{CC}$	6.0 V
$C_L$	30 pF	50 pF

Note: 1.  $C_L$  includes probe and jig capacitance.

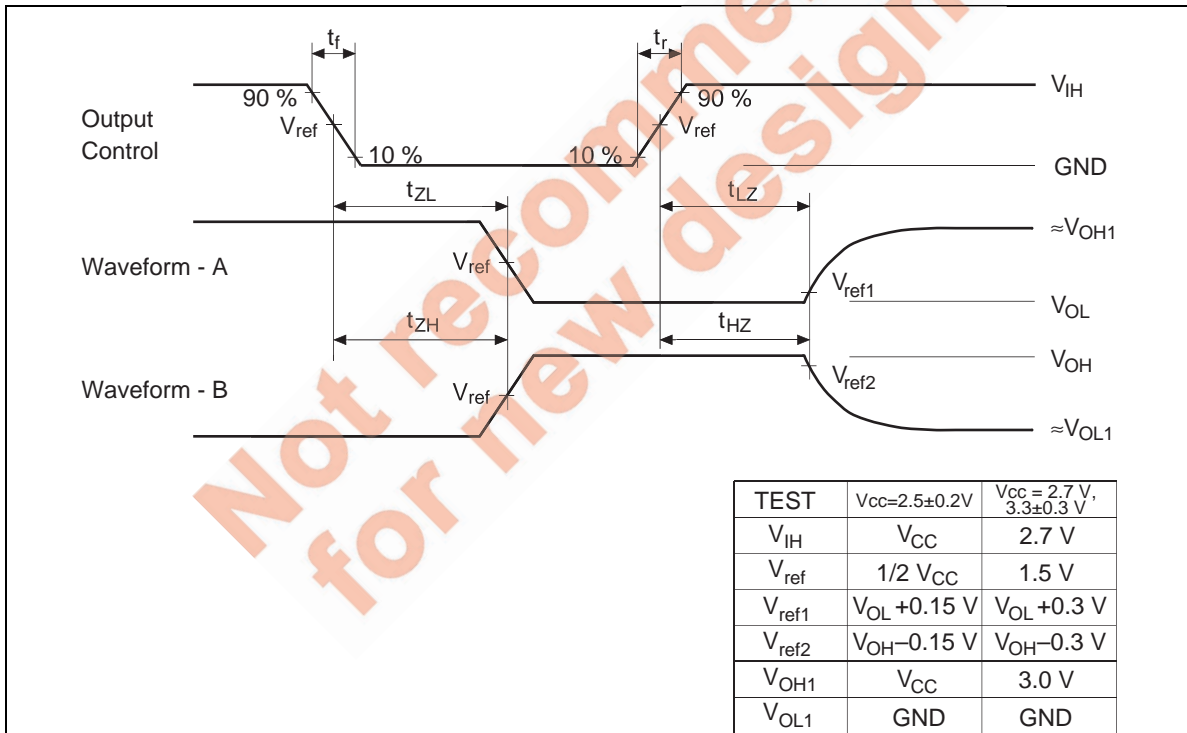
Not recommended for new design



Waveforms - 1

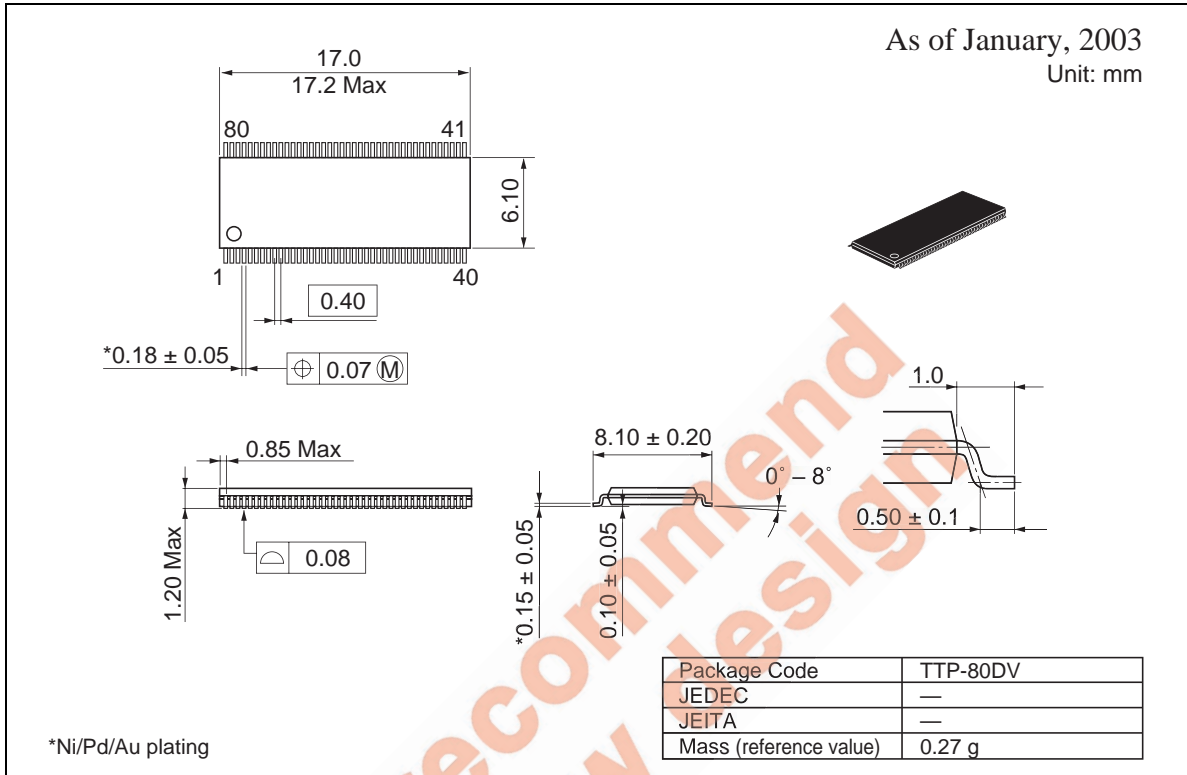


Waveforms - 2



- Notes:
- All input pulses are supplied by generators having the following characteristics :  
 $PRR \leq 10 \text{ MHz}$ ,  $Z_o = 50 \Omega$ ,  $t_r \leq 2.0 \text{ ns}$ ,  $t_f \leq 2.0 \text{ ns}$ . ( $V_{CC} = 2.5\pm 0.2 V$ )  
 $PRR \leq 10 \text{ MHz}$ ,  $Z_o = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ . ( $V_{CC} = 2.7 V, 3.3\pm 0.3 V$ )
  - Waveform – A is for an output with internal conditions such that the output is low except when disabled by the output control.
  - Waveform – B is for an output with internal conditions such that the output is high except when disabled by the output control.
  - The output are measured one at a time with one transition per measurement.

Package Dimensions



## RENESAS Technology Corp. Sales Strategic Planning Div. Nippon Bldg., 2-6-2, Ohte-machi, Chiyoda-ku, Tokyo 100-0004, Japan

Keep safety first in your circuit designs!

1. Renesas Technology Corp. puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage.  
Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of nonflammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

1. These materials are intended as a reference to assist our customers in the selection of the Renesas Technology Corp. product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Renesas Technology Corp. or a third party.
2. Renesas Technology Corp. assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
3. All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Renesas Technology Corp. without notice due to product improvements or other reasons. It is therefore recommended that customers contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor for the latest product information before purchasing a product listed herein.  
The information described here may contain technical inaccuracies or typographical errors.  
Renesas Technology Corp. assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.  
Please also pay attention to information published by Renesas Technology Corp. by various means, including the Renesas Technology Corp. Semiconductor home page (<http://www.renesas.com>).
4. When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Renesas Technology Corp. assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
5. Renesas Technology Corp. semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Renesas Technology Corp. or an authorized Renesas Technology Corp. product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
6. The prior written approval of Renesas Technology Corp. is necessary to reprint or reproduce in whole or in part these materials.
7. If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.  
Any diversion or reexport contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
8. Please contact Renesas Technology Corp. for further details on these materials or the products contained therein.



### RENESAS SALES OFFICES

<http://www.renesas.com>

**Renesas Technology America, Inc.**  
450 Holger Way, San Jose, CA 95134-1368, U.S.A  
Tel: <1> (408) 382-7500 Fax: <1> (408) 382-7501

**Renesas Technology Europe Limited.**  
Dukes Meadow, Millboard Road, Bourne End, Buckinghamshire, SL8 5FH, United Kingdom  
Tel: <44> (1628) 585 100, Fax: <44> (1628) 585 900

**Renesas Technology Europe GmbH**  
Dornacher Str. 3, D-85622 Feldkirchen, Germany  
Tel: <49> (89) 380 70 0, Fax: <49> (89) 929 30 11

**Renesas Technology Hong Kong Ltd.**  
7/F., North Tower, World Finance Centre, Harbour City, Canton Road, Hong Kong  
Tel: <852> 2265-6688, Fax: <852> 2375-6836

**Renesas Technology Taiwan Co., Ltd.**  
FL 10, #99, Fu-Hsing N. Rd., Taipei, Taiwan  
Tel: <886> (2) 2715-2888, Fax: <886> (2) 2713-2999

**Renesas Technology (Shanghai) Co., Ltd.**  
26/F., Ruijin Building, No.205 Maoming Road (S), Shanghai 200020, China  
Tel: <86> (21) 6472-1001, Fax: <86> (21) 6415-2952

**Renesas Technology Singapore Pte. Ltd.**  
1, Harbour Front Avenue, #06-10, Keppel Bay Tower, Singapore 098632  
Tel: <65> 6213-0200, Fax: <65> 6278-8001